

HD81901

Single Chip Modem Supporting V.27ter/bis and V.26/bis

Description

The HD81901 is a single chip CMOS LSI modem based on the CCITT V.27ter/bis and V.26/bis standards. It can be used in the All Japan Bank network protocol, in the JCA protocol, and in JUST-PC, PC, CAPTAIN, and general data communications. This LSI incorporates modulator and demodulator circuits, transmission and reception filters, a V.24 interface, and the other circuits necessary in a modem. By using this LSI, a modem system for use in PC and data communications can be constructed easily.

Features

- Can handle the All Japan Bank, JCA, JUST-PC, and CAPTAIN protocols
- CCITT standards
V.26, V.26bis
V.27ter, V.27bis
V.23 (BWC)
- Four wire full duplex and two wire half duplex operation
- Built-in transmission and reception filters
- Transmission and detection of all tone types (Arbitrary frequency transmission and detection possible)
- Built-in DTMF generator
- Transmission level adjustment possible (0 dBm to -31 dBm)
- Reception level adjustment possible
- Three type of equalizer built in
 - Adaptive auto-equalizer
 - Subscriber line equalizer
 - Fixed delay equalizer (2 links)
- NCU control pins (3 inputs and 3 outputs)
- Loop test
- Eye pattern generation signal output available

- Low power CMOS (350 mW typ.)
- Wide operating temperature range (-20 to +75 °C)
- Single voltage +5 V power supply
- Package lineup includes:
 - 64 pin plastic shrink DIP (DP-64S)
 - 80 pin QFP (FP-80B)
 - 68 pin PLCC (CP-68)

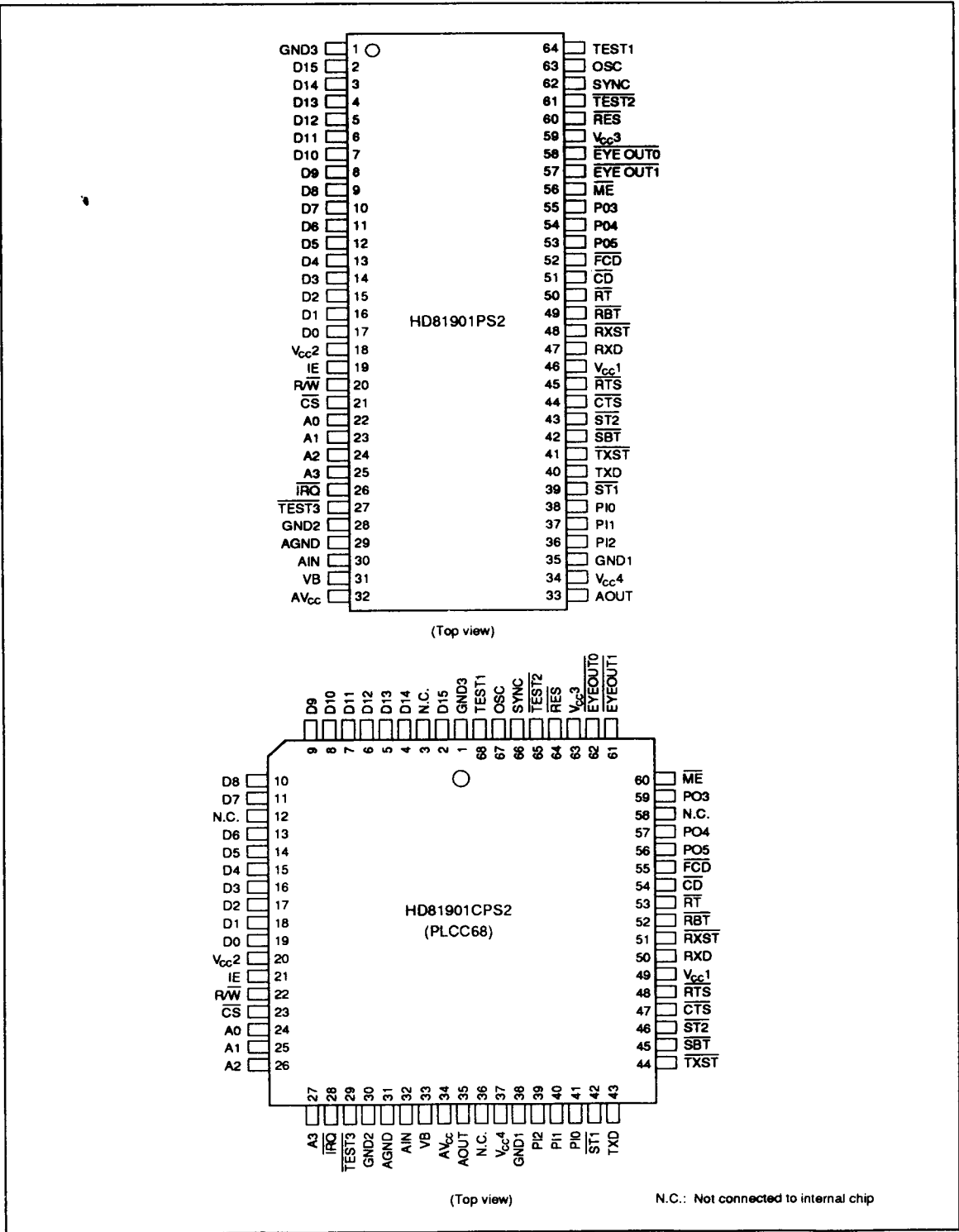
Functions

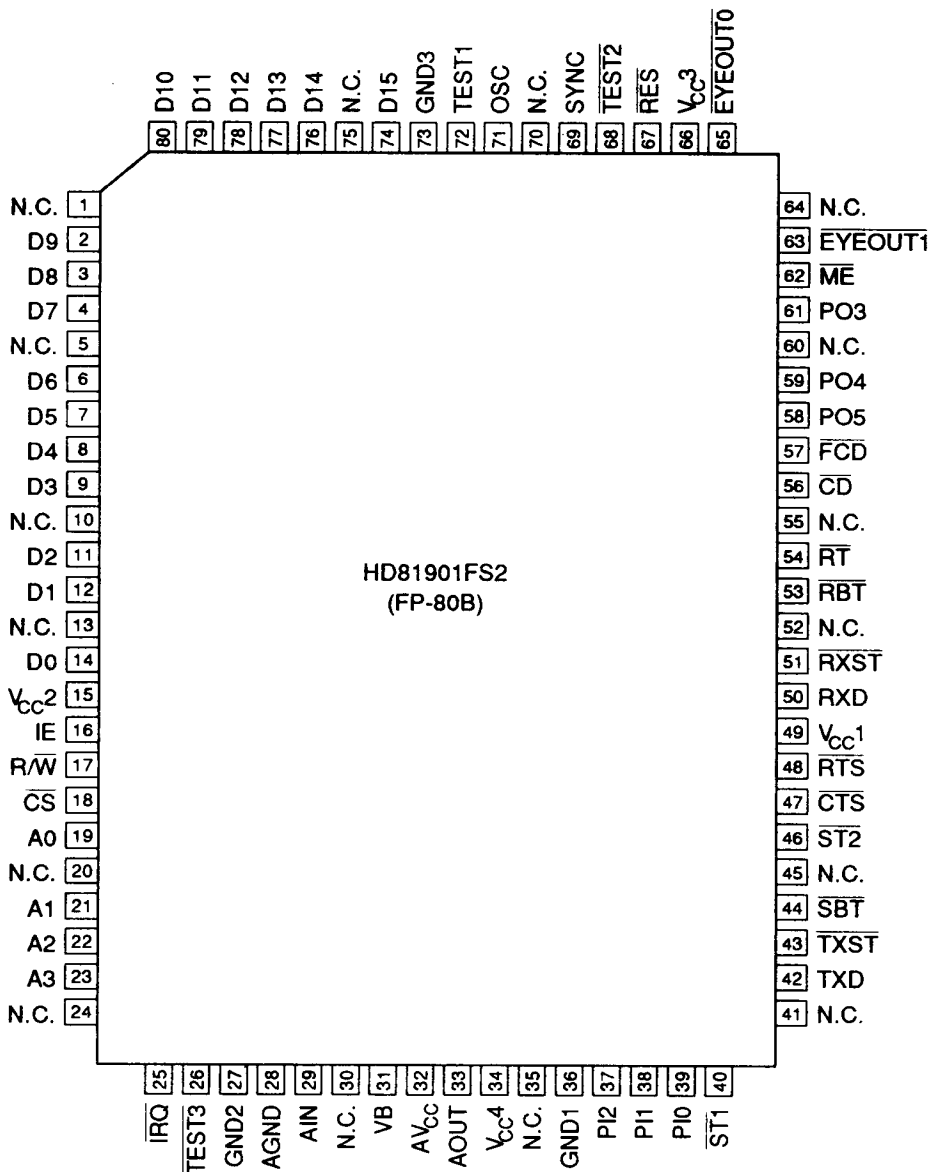
- CCITT standards (Data transmission speeds)
 - V.27ter: 4.8k/2.4k bps
 - V.27bis: 4.8k/2.4k bps
 - V.26bis: 2.4k/1.2k bps
 - V.26: 2.4k bps
 - V.23 (BW): 75 bps
- Training signal
V.27ter/bis: long/short
- DTMF signal transmission
Level difference between higher and lower group frequency settable
- Transmission and detection of all tone types
2100 Hz (default), 1800 Hz (default), 400 Hz (default) and arbitrarily settable detection frequency

Product Lineup

Catalogue Number	Package
HD81901PS2	DP-64S
HD81901CPS2	CP-68
HD81901FS2	FP-80B

Pin Layout Diagrams





(Top view)

N.C.: Not connected to internal chip

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Electrical Characteristics

Absolute Maximum Ratings

Item	Symbol	Rated Value	Units
Power supply voltage *1	V_{CC}	-0.3 to +7.0	V
Analog power supply voltage	AV_{CC}	-0.3 to +7.0	V
Digital power supply voltage	V_{IND}	-0.3 to $V_{CC} + 0.3$	V
Analog input voltage	V_{INA}	-0.3 to $V_{CC} + 0.3$	V
Operating temperature	T_{DDR}	-20 to ± 75	°C
Storage temperature	T_{stg}	-55 to +125	°C
Storage temperature (when bias voltage applied)	T_{bias}	-20 to +85	°C

Note: *1. $V_{CC1} = V_{CC2} = V_{CC3} = V_{CC4} = AV_{CC}$ GND1 = GND2 = GND3 = AGND

DC Characteristics ($V_{CC1} = V_{CC2} = V_{CC3} = V_{CC4} = AV_{CC} = 5.0 \text{ V} \pm 5\%$, GND1 = GND2 = GND3 = AGND = 0 V, $T_a = -20$ to $+75^\circ\text{C}$, unless otherwise noted)

Item	Symbol	Min.	Typ.	Max.	Units	Applicable Pins	Measurement Conditions
Digital input high level voltage	V_{IH1}	2.4	—	$V_{CC} + 0.3$	V	OSC	
	V_{IH2}	2.4	—	$V_{CC} + 0.3$	V	*1	
	V_{IH3}	$V_{CC} \times 0.7$	—	$V_{CC} + 0.3$	V	$\overline{\text{RES}}$	
Digital input low level voltage	V_{IL1}	-0.3	—	0.6	V	OSC	
	V_{IL2}	-0.3	—	0.6	V	*1	
	V_{IL3}	-0.3	—	0.6	V	$\overline{\text{RES}}$	
Digital input leakage current	$ I_{in} $	—	—	10	μA	*1 OSC	$V_{IN} = 0.4\text{--}2.4 \text{ V}$
Digital three state (off state) current	$ I_{Tst} $	—	—	10	μA	*2	$V_{IN} = 0.4\text{--}2.4 \text{ V}$
Digital output high level voltage	V_{OH}	2.4	—	—	V	*3	$-I_{OH} = 400 \mu\text{A}$
Digital output low level voltage	V_{OL}	—	—	0.4	V	*3	$I_{OL} = 1.6 \text{ mA}$
Pull-up current	I_{PULL}	—	—	400	μA	*4	$V_{IN} = 0 \text{ V}$
Analog input leakage current	$ I_{IA} $	—	—	10	μA	A_{IN}	$V_{IN} = 0 \text{ V}$
	$ I_{IA} $	—	—	10	μA	A_{IN}	$V_{IN} = AV_{CC} = 5.0 \text{ V}$
Analog input resistance	R_{IA}	1	—	—	$\text{M}\Omega$	A_{IN}	$f = 1 \text{ kHz}$
Analog output resistance	R_{OA}	—	—	100	Ω	A_{OUT}	
Power dissipation	I_{CC}	—	70	—	mA		

DC Characteristics ($V_{CC1} = V_{CC2} = V_{CC3} = V_{CC4} = AV_{CC} = 5.0 \text{ V} \pm 5\%$, $GND1 = GND2 = GND3 = AGND = 0 \text{ V}$, $T_a = -20 \text{ to } +75^\circ\text{C}$, unless otherwise noted) (cont)

Item	Symbol	Min.	Typ.	Max.	Units	Applicable Pins	Measurement Conditions
Analog reference power supply voltage	V_B	2.3	2.4	2.55	V	V_B	
Analog reference power supply current	I_B	—	—	10	μA	V_B	$V_B = 2.55 \text{ V}$
Digital input capacitance	C_{IN}	—	—	12.5	pF	All input pins other than A_{IN}	$f = 1 \text{ MHz}$ $V_{IN} = 0 \text{ V}$ $T_a = 25^\circ\text{C}$
Analog input capacitance	C_{IA}	—	—	40	pF	A_{IN}	$f = 1 \text{ MHz}$, $V_B = 2.4 \text{ V}$
Analog output offset voltage	$V_{O\text{OFF}}$	-220	—	220	mV	A_{OUT}	
Analog input max. voltage	$V_{A\text{Imax}}$	—	—	2.2	V_{PP}	A_{IN}	$V_B = 2.4 \text{ V}$
Analog output max. voltage	$V_{A\text{Omax}}$	2.2	—	—	V_{PP}	A_{OUT}	When $R_L = 10 \text{ k}\Omega$ or over, $V_B = 2.4 \text{ V}$, $C_L = 10 \text{ pF}$ or less, external +10 dB.

Notes: *1. $\overline{\text{TXD}}$, $\overline{\text{ST1}}$, $\overline{\text{RTS}}$, $\overline{\text{ME}}$, PI0-PI2 , D0-D15 , A0-A3 , $\overline{\text{R}\overline{\text{W}}}$, $\overline{\text{CS}}$, IE

*2. D0-D15

*3. $\overline{\text{RXD}}$, $\overline{\text{RBT}}$, $\overline{\text{ST2}}$, $\overline{\text{SBT}}$, $\overline{\text{RT}}$, $\overline{\text{CTS}}$, $\overline{\text{CD}}$, $\overline{\text{FCD}}$, $\overline{\text{IRQ}}$, $\overline{\text{EYEOUT0-EYEOUT1}}$, PO3-PO5 , SYNC , $\overline{\text{TXST}}$, $\overline{\text{RXST}}$, D0-D15

*4. $\overline{\text{IRQ}}$, ST1 , $\overline{\text{RTS}}$, PI0-PI2 , $\overline{\text{ME}}$, $\overline{\text{RES}}$, $\overline{\text{TEST2}}$, $\overline{\text{TEST3}}$

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AC Characteristics ($V_{CC1} = V_{CC2} = V_{CC3} = V_{CC4} = AV_{CC} = 5.0\text{ V} \pm 5\%$, $GND1 = GND2 = GND3 = AGND = 0\text{ V}$, $T_a = -20\text{ to }+75^\circ\text{C}$, unless otherwise noted)

Item	Symbol	Min.	Typ.	Max.	Units	Applicable Pins	Figures
OSC cycle time	ϕ_{CYC}	—	33.9	—	ns		Refer to figure 19 *1
OSC pulse width	ϕ_{WH}, ϕ_{WL}	10	—	—	ns		
OSC rise/fall times	ϕ_r, ϕ_f	—	—	5	ns		
IE cycle time	t_{CYC}	0.5	—	—	μs		Refer to figure 15
IE pulse width high level	t_{WH}	210	—	—	ns		
IE pulse width low level	t_{WL}	210	—	—	ns		
IE rise time	t_r	—	—	25	ns		
IE fall time	t_f	—	—	25	ns		
CS set up time	t_{CS}	45	—	—	ns		
CS hold time	t_{CH}	10	—	—	ns		
Input data set up time	t_{DSW}	60	—	—	ns		Refer to figure 16
Input data hold time	t_{DHW}	10	—	—	ns		
Output data delay time	t_{DDR}	—	—	150	ns		
Output data hold time	t_{DHR}	20	—	—	ns		
Reset puls width	t_{RST}	0.5	—	—	μs		
Serial input data (TXD) set up time	t_{TXS}	200	—	—	ns	TXD	Refer to figure 17
Serial input data (TXD) hold time	t_{TXH}	200	—	—	ns	TXD	
ST1 rise time	S_r	—	—	500	ns	$\overline{ST1}$	Refer to figure 18
ST1 fall time	S_f	—	—	500	ns	$\overline{ST1}$	
Serial output data (RXD) delay time	t_{RXD}	—	—	250	ns	RXD	

Note: *1: OSC = 29.4912 MHz (deviation less than 100 ppm)

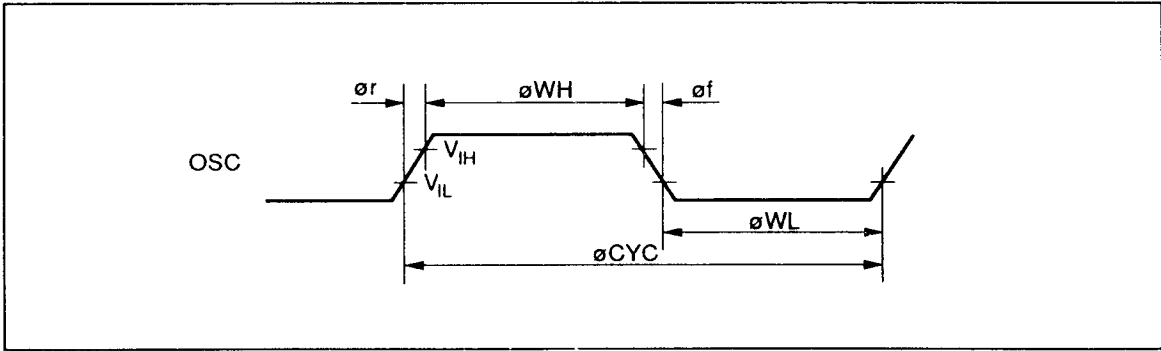


Figure 19 Reference Clock Waveform